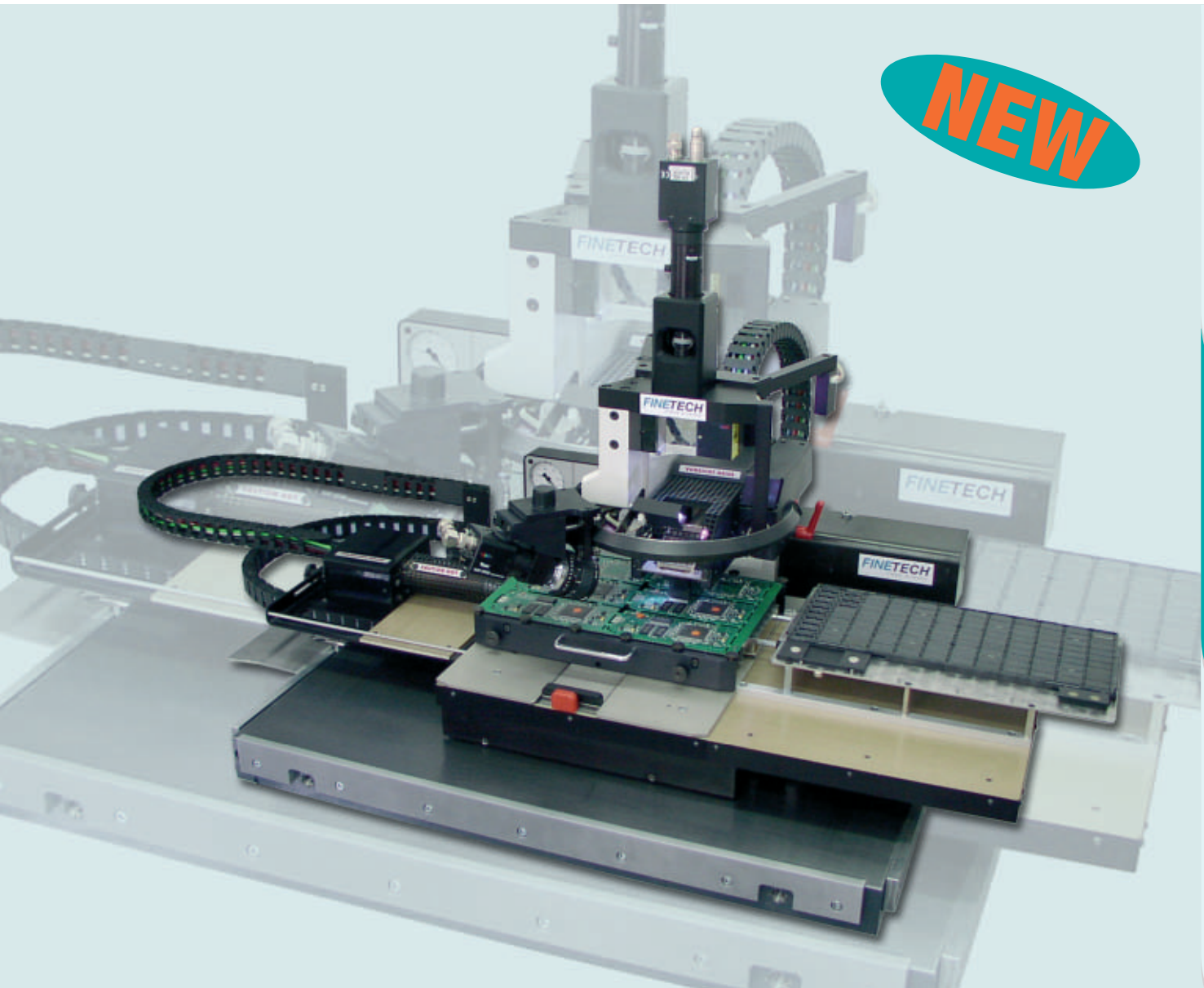


FINEPLACER[®] SYSTEM

AUTOMATIC REWORK



FINEPLACER SYSTEM

REWORK

FLIPCHIP

The patented **FINEPLACER[®]** platform with added vision alignment system (VAS) forms the basis for the automatic Rework System. Based on a stationary beam splitter, the tools' reliability has been proven with several hundred worldwide installations.

A highly accurate, and "friction-free" x,y planar table is integrated with high resolution z axis control. An additional

fast linear table movement enables large substrates to be accommodated, as well as a provision for component storage in trays or waffle paks. Likewise, the FINETECH pivot arm with component rotation capability is automated for hands-free placement.

Sensors on the pivot arm allow component placement with defined force via z-axis motion of the substrate, providing

a complete **Rework Process** including the patented "single-sweep" residual solder removal technique.

Placement Accuracy

The automatic FINEPLACER[®] System has a placement accuracy of better than **10 µm**, sufficient for the highest µBGA, CSP and Flip Chip demands.

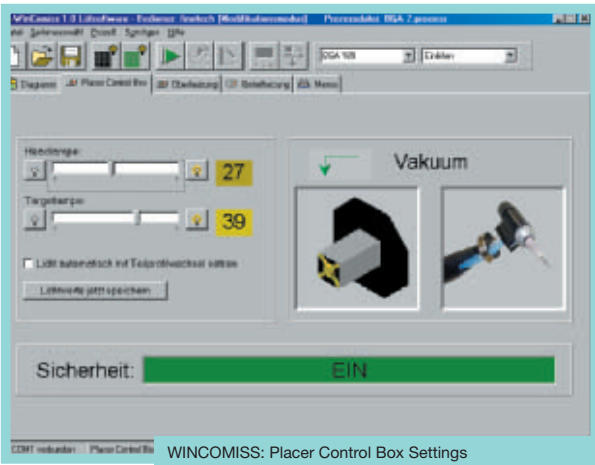
FINETECH
...simply accurate

FINEPLACER[®] SYSTEM

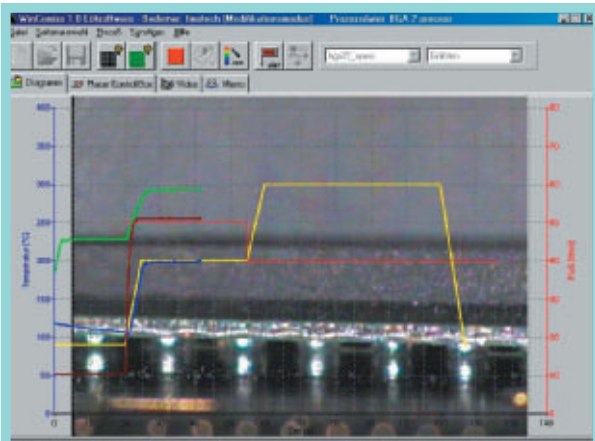
AUTOMATIC REWORK



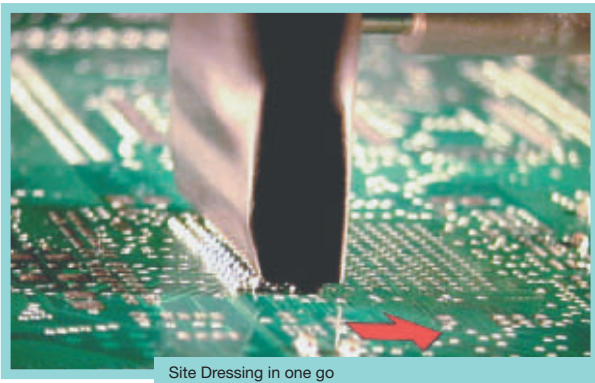
x,y - Linear Table with Integrated z-Axis



WINCOMISS: Placer Control Box Settings



WINCOMISS: Reflow Program with Real Time Process Observing Image



Site Dressing in one go

Automatic Alignment

The VAS integrated into the FINEPLACER[®] System, in combination with the pattern recognition module allows the automatic alignment of PCB and component.

Hot Gas Soldering Module COMISS IV

The new hot-gas soldering module COMISS IV (Controlled Mix Soldering System) uses a Windows[®] based menu-driven interface to reproducibly control gas flow rate and solder temperature. The soldering module COMISS IV is compatible with the unleaded soldering process.

User Friendly Operation

System operation is achieved by joystick control and Windows[®] based multi-tasking operation system with graphical user interface. Besides the automated processing of small lots, added flexibility is provided by the "Teach-in-Mode" to evaluate and learn new processes.

Flexibility and Modularity

In addition to the availability as a automatic system, existing manual systems can be upgraded with selected motorised modules. Please ask for outlines of our FINETECH processing modules for Rework and Flip-chip processes.

Technical Data

x,y Planar table

Travel range	380 x 155 mm
Component insertion area	280 x 155 mm
Additional movement in x direction	250 mm
Resolution	0,625 µm
Repeat accuracy	< ± 2,5 µm

z-axis

Travel range	8 mm
Resolution	0,8 µm
Repeat accuracy	< ± 10 µm

Theta-axis

Travel range	±3°
Resolution	3,2"

Pivot / swing module

Travel range	90° +2°
Resolution	2,7"
Repeat accuracy	< ± 25"

Distributor:

www.finetech.de